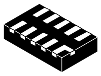
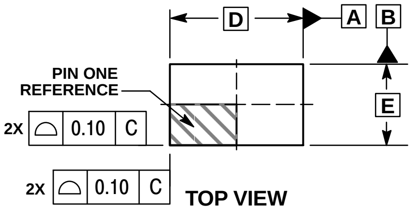


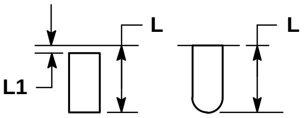
**SCALE 4:1**

# XDFN10 2.2x1.35, 0.4P
CASE 711AU
ISSUE B

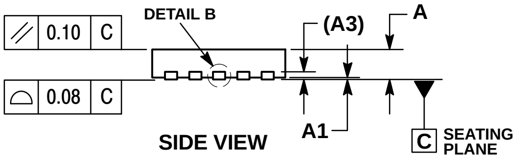
DATE 17 JUN 2014



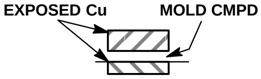
TOP VIEW



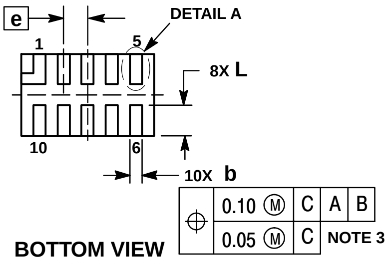
**DETAIL A**
ALTERNATE CONSTRUCTIONS



SIDE VIEW



**DETAIL B**
ALTERNATE CONSTRUCTION

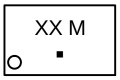


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.

| | MILLIMETERS | |
|---|---|---|
| DIM | MIN | MAX |
| A | 0.40 | 0.50 |
| A1 | 0.00 | 0.05 |
| A3 | 0.15 REF | |
| b | 0.15 | 0.25 |
| D | 2.20 BSC | |
| E | 1.35 BSC | |
| e | 0.40 BSC | |
| L | 0.40 | 0.60 |
| L1 | --- | 0.15 |

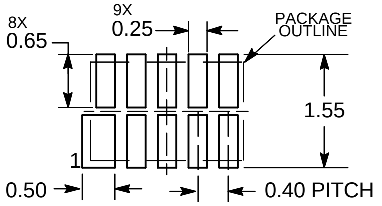
## GENERIC MARKING DIAGRAM*



| | |
|---|---|
| XX | = Specific Device Code |
| M | = Date Code |
| ▪ | = Pb−Free Package |

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

## RECOMMENDED MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

| | | |
|---|---|---|
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| NEW STANDARD: | | |
| DESCRIPTION: | XDFN10 2.2X1.35, 0.4P | PAGE 1 OF 2 |

| ON Semiconductor® | DOCUMENT NUMBER:<br>98AON83517F<br>PAGE 2 OF 2 |
|---|---|

| ISSUE | REVISION | DATE |
|---|---|---|
| O | RELEASED FOR PRODUCTION. REQ. BY D. TRUHITTE. | 19 MAR 2014 |
| A | CHANGED DIMENSION A3 FROM 0.13 TO 0.15. REQ. BY D. TRUHITTE. | 04 JUN 2014 |
| B | SEPARATED PREVIOUSLY FUSED PINS 3 AND 8. REQ. BY D. TRUHITTE. | 17 JUN 2014 |
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